

# **SPECIFICATION**

# FOR LCD MODULE

MODEL NO:	TM12864J1CCWGWA
CUSTOMER:	
CUSTOMER P/N.	
VERSION	V0.0
CUSTOMER	
APPROVED	

- Preliminary specification
- □ Final specification

PREPARED BY	CHECKED BY	VERIFIED BY QA DEPT.	APPROVED BY

### TIANMA MICRO-ELECTRONICS CO., LTD

Address: 8F, 64th Building, Jinlong, Majialong Industrial Area, Nanshan District, Shenzhen, China Tel: +86-755-26094288 Fax: +86-755-86225774

Web: www.tianma.cn www.tianma.com





# **REVISION RECORD**

Version	Page	Revision Items	Name	Date
0.0	1	First release	WP	2009.5.31



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# 1 Description

The TM12864J1CCWGWA LCM unit consists of  $128\times64$  dot-matrix LCD, and a single-chip S7567 which incorporates LCD controller and common/segment driver. This module can be connected directly to microprocessor with 4-line serial interface or 8-bit parallel interface. Built in a RAM with  $65\times132$ -bit capacity for storing the display data, so the unit can efficiently display the desired content under microprocessor control.

- Wide Operating temperature.
- Requirements on environmental protection: RoHS.

#### 2 Features

Item	Contents
LCD type	FSTN
LCD type	Positive
LCD Duty	1/65
LCD Bias	1/9
Polarizer	transflective
LCD background color	white
Segment color	black
Backlighting	LED
Backlighting type	edge
Backlighting color	white
Backlighting drive	4.0 V(TYPE),I=60mA
View direction	6:00
Operating temperature	-20℃~70℃
Storage temperature	-30℃~80℃
Controller	ST7567
Technology	COG
Power supply	VDD=3.0V
Data Transfer	8 Bit Parallel or SPI

#### Notes:

- Color tone can slightly change with temperature and driving voltage.
- Color tone will be changed by backlight.



3 Absolute maximum ratings

(Without LED backlighting ,Ta=25 °C)

Parameter	Symbol	Min	Max	Unit	Remark
Logic circuit supply voltage	$V_{DD}$	-0.3	3.6	V	
LCD driving voltage	$V_{LCD}$	-0.3	16	V	
Operating temperature range	Тор	-20	+70	$^{\circ}\!$	No Condensatio
Storage temperature range	Tst	-30	+80	$^{\circ}\! \mathbb{C}$	n

# Note:

- LCD operating voltage V<sub>LCD</sub> measured between XV0and V0 pins.
- If the module is above these absolute maximum ratings. It may become permanently damaged.

# **4 Mechanical Characteristics**

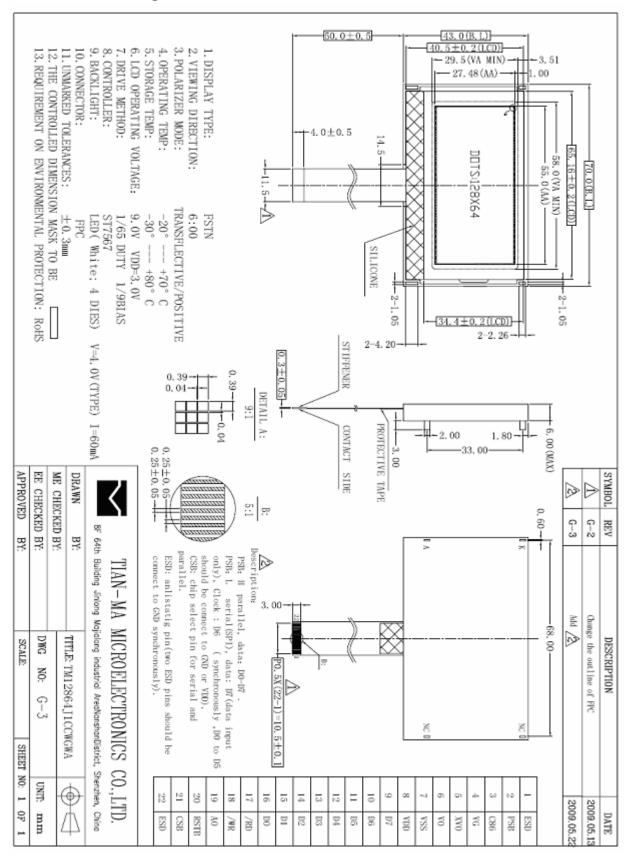
# 4.1 Mechanical features

Parameter	Standard Value	Unit
Display type	Graphics module	
Character size(W×H)	÷	mm
Number of dots/characters (W×H)	128X64	
View area (W×H)	58.0X29.5	mm
Active Area (W×H)	55.0X27.48	mm
Dot Size (W×H)	0.39X0.39	mm
Dot Pitch (W×H)	0.43X0.43	mm
Module size(W×H×D)	70.0X43.0X6.0 (MAX) *	mm
Module total weight (approx)		g
Module outline dimensions	Refer to page 5-"Mechanical drawing"	

NOTE: Exclude the length of the FPC



# 4.2 Mechanical drawing.

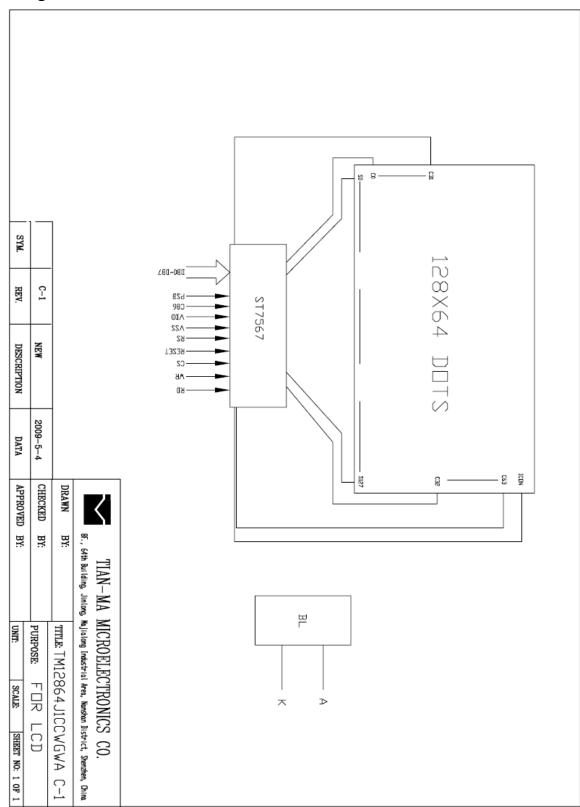


Rob



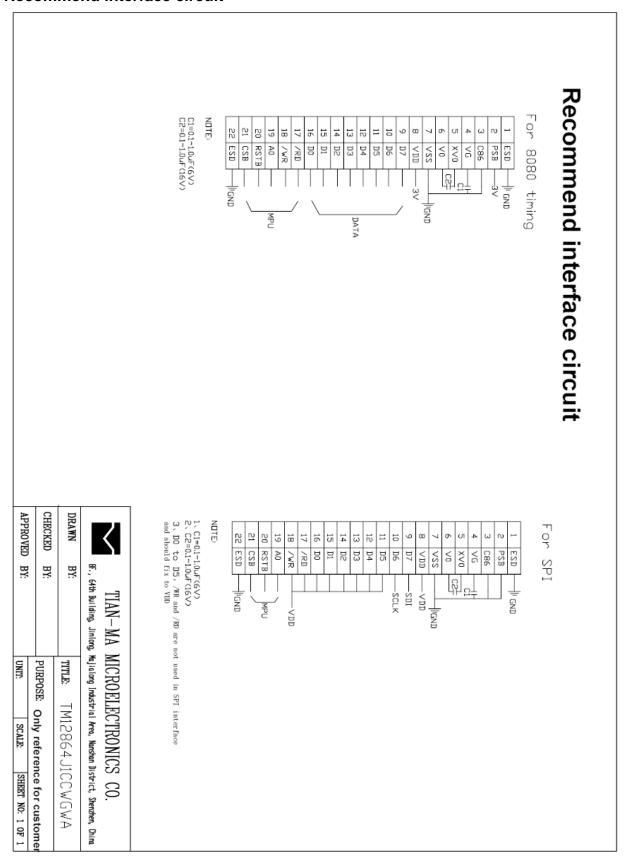
# **5 Circuit**

# 5.1 Block Diagram





# 5.2 Recommend interface circuit





# 6 Interface description.

Pin No.	Symbol	I/O	Description
1	ESD	1	Anlistatig pin ,connect to GND
2	PSB	1	Interface type select pin(L:SPI H: Parallel)
3	C86	1	C86 selects the microprocessor type in parallel interface mode.
4	VG	Р	VG is the LCD driving voltage for segment circuits.
5	XV0	Р	XV0 is the LCD driving voltage for common circuits at positive frame.
6	V0	Р	V0 is the LCD driving voltage for common circuits at negative frame.
7	VSS	0V	GND
8	VDD	3.0V	Power supply voltage for logic
9	D7	I/O	Data bit7
10	D6	I/O	Data bit6
11	D5	I/O	Data bit5
12	D4	I/O	Data bit4
13	D3	I/O	Data bit3
14	D2	I/O	Data bit2
15	D1	I/O	Data bit1
16	D0	I/O	Data bit0
17	/RD	I	Read/Write execution control pin.
18	/WR	I	Read/Write execution control pin.
19	A0	Ι	data or command select pin
20	RSTB	I	Hardware reset input pin.
21	CSB	I	Chip select input pin.
22	ESD	I	Anlistatig pin, connect to GND



# 7 Instruction Code & Timing characteristics

# 7.1 COMMAND

The table below lists the types of commands, including the code of each command. more details refer toST7567 data sheet please.

		R/W	COMMAND BYTE									
INSTRUCTION	A0	(RWR)	D7	D6	D5	D4	D3	_ D2	D1	D0	DESCRIPTION	
(1) Display ON/OFF	0	0	1	0	1	0	1	1	1	D	D=1, display ON D=0, display OFF	
(2) Set Start Line	0	0	0	1	S5	S4	S3	S2	S1	S0	Set display start line	
(3) Set Page Address	0	0	1	0	1	1	Y3	Y2	Y1	Y0	Set page address	
(4)	0	0	0	0	0	1	Х7	X6	X5	X4	Set column address (MSB)	
Set Column Address	0	0	0	0	0	0	X3	X2	X1	X0	Set column address (LSB)	
(5) Read Status	0	1	0	MX	D	RST	0	0	0	0	Read IC Status	
(6) Write Data	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write display data to RAM	
(7) Read Data	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read display data from RAM	
(8) SEG Direction	0	0	1	0	1	0	0	0	0	MX	Set scan direction of SEG MX=1, reverse direction MX=0, normal direction	
(9) Inverse Display	0	0	1	0	1	0	0	1	1	IN∨	INV =1, inverse display INV =0, normal display	
(10) All Pixel ON	0	0	1	0	1	0	0	1	0	AP	AP=1, set all pixel ON AP=0, normal display	
(11) Bias Select	0	0	1	0	1	0	0	0	1	BS	Select bias setting 0=1/9; 1=1/7 (at 1/65 duty)	
(12) Read-modify-Write	0	0	1	1	1	0	0	0	0	0	Column address increment: Read:+0 , Write:+1	
(13) END	0	0	1	1	1	0	1	1	1	0	Exit Read-modify-Write mode	
(14) RESET	0	0	1	1	1	0	0	0	1	0	Software reset	
(15) COM Direction	0	0	1	1	0	0	MY	-	-	-	Set output direction of COM MY=1, reverse direction MY=0, normal direction	
(16) Power Control	0	0	0	0	1	0	1	VB	VR	VF	Control built-in power circuit ON/OFF	
(17) Regulation Ratio	0	0	0	0	1	0	0	RR2	RR1	RR0	Select regulation resistor ratio	
(40) Cot EV	0	0	1	0	0	0	0	0	0	1	Double command!! Set	
(18) Set EV	0	0	0	0	EV5	EV4	EV3	EV2	EV1	EV0	electronic volume (EV) level	
	0	0	1	1	1	1	1	0	0	0	Double command!!	
(19) Set Booster	0	0	0	0	0	0	0	0	0	BL	Set booster level: BL=0: 4X BL=1: 5X	
(20) Power Save	0	0			Co	mpound	Comm	and			Display OFF + All Pixel ON	
(21) NOP	0	0	1	1	1	0	0	0	1	1	No operation	
(22) Test	0	0	1	1	1	1	1	1	1	-	Do NOT use. Reserved for testing.	

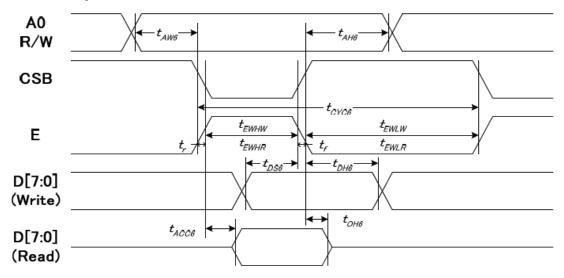
Note: Symbol "-" means this bit can be "H" or "L".



# 7.2 Interface Timing characteristics

Note: Please refer to IC: ST7567 data sheet for more details.

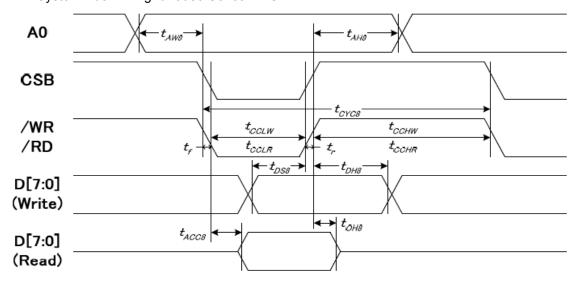
7.2.1 System Bus Timing for 6800 Series MPU



VDD=3.0V Ta=25℃

ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	- A0	tAW6		0	_	
Address hold time	Au	tAH6		0	_	1
System cycle time		tCYC6		400	_	1
Enable L pulse width (WRITE)		tEWLW		220	_	1
Enable H pulse width (WRITE)	E	tEWHW		180	_	1
Enable L pulse width (READ)		tEWLR		220	_	ns
Enable H pulse width (READ)		tEWHR		180	_	1
Write data setup time		tDS6		40	_	1
Write data hold time	D(7:01	tDH6		20	_	1
Read data access time	D[7:0]	tACC6	CL = 16 pF	_	140	]
Read data output disable time		tOH6	CL = 16 pF	10	100	

# 7.2.2 System Bus Timing for 8080 Series MPU

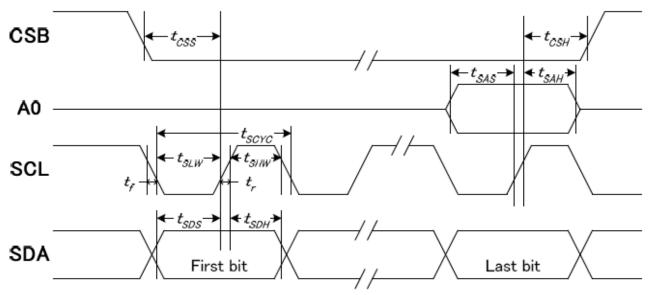




# VDD=3.0V Ta=25℃

ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	A0	tAW8		0	_	
Address hold time	Au	tAH8		0	_	
System cycle time		tCYC8		400	_	
/WR L pulse width (WRITE)	WR	tCCLW		220	_	
/WR H pulse width (WRITE)		tCCHW		180	_	
/RD L pulse width (READ)	DD	tCCLR		220	_	ns
/RD H pulse width (READ)	RD	tCCHR		180	_	1
WRITE Data setup time		tDS8		40	_	
WRITE Data hold time	D(7:01	tDH8		20	_	
READ access time	D[7:0]	tACC8	CL = 16 pF	_	140	1
READ Output disable time		tOH8	CL = 16 pF	10	100	1

# 7.2.3 System Bus Timing for 4-Line Serial Interface

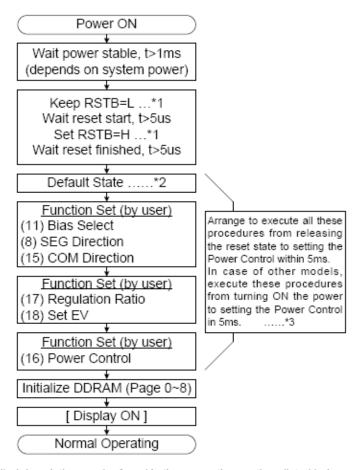


VDD=3.0V Ta=25 °C

ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Serial clock period		tSCYC		100	_	
SCLK "H" pulse width	SCLK	tSHW		50	_	
SCLK "L" pulse width		tSLW		50	_	
Address setup time	A0	tSAS		30	_	
Address hold time		tSAH		20	_	ns
Data setup time	SDA	tSDS		30	_	
Data hold time	SDA	tSDH		20	_	
CSB-SCLK time	CSB	tCSS		30	_	
CSB-SCLK time	CSB	tCSH		60	_	



# 7.3 Initialization flow map



Note: The detailed description can be found in the respective sections listed below.

- Please refer to the timing specification of t<sub>RW</sub> and t<sub>R</sub>.
- 2. Refer to Section 7. RESET CIRCUIT.
- The 5ms requirement depends on the characteristics of LCD panel and the external component of the power circuit. It is recommended to check with the real products with external component.
- 4. The detailed instruction functionality is described in Section 9. INSTRUCTION DESCRIPTION;
- 5. Power stable is defined as the time that the later power (VDDI or VDDA) reaches 90% of its rated voltage.

#### Timing Requirement:

Item	Symbol	Requirement	Note
			Applying VDDI and VDDA in any order will not damage IC.
VDDA power delay	t <sub>ON-V2</sub>	$0 \le t_{ON-V2}$	The requirement listed here is to prevent abnormal display
			on LCD module.
		No Limitation	RSTB=L can be input at any time after power is stable.
	t <sub>on-RST</sub>		<ul> <li>t<sub>RW</sub> &amp; t<sub>R</sub> should match the timing specification of RSTB.</li> </ul>
			To prevent abnormal display, the recommended timing is:
RSTB input time			0 ≤ t <sub>ON-RST</sub> ≤ 30 ms.
			If RSTB is high or unstable during power ON, a successful
			hardware reset by RSTB is required after VDDI and VDDA
			are both stable (like Case-2).

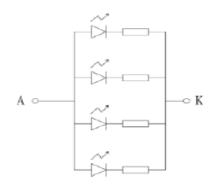


# 8 Electrical characteristics

V<sub>SS</sub>=0V, Ta=25℃

Parameter		Symbol	Condition	MIN	TYP	MAX	UNIT
Logic circuit supply voltage		$V_{DD}$		2.7	3.0	3.3	
Power supply LCD		$V_{lcd}$		8.8	9.0	9.2	
Input voltage for	"H"level	V <sub>IH</sub>		0.7X VDD		VDD	V
logic circuit	"L"level	V <sub>IL</sub>		0		0.3XVDD	V
Output voltage for	"H"level	V <sub>OH</sub>	<del></del>	0.7XV DD		VDD	
logic circuit	"L"level	V <sub>OL</sub>		0		0.3XVDD	
Logic power supply current (Without backlighting)		I <sub>CC</sub>	-			2.0	mA
Used driver IC		ST7567					

# 9 LED backlight characteristics



# Circuit diagram (LED 1x4=4 dies)

Item	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Forward voltage	V <sub>f</sub>		3.8	4.0	4.2	٧
Luminance	Вр		280	380	510	cd/m <sup>2</sup>
Average		I <sub>f</sub> =60mA	75			%
Color coordinate*	Х		0.265		0.315	
Color coordinate	Y		0.265		0.315	

#### Note:

- Measured at the bare LED backlight unit.
- If the backlight is above these maximum ratings for long time, the service life of the LED backlight will reduce or it will cause poor reliability.



# **10 Optical Characteristics**

# 10.1 Optical Characteristics

Ta=25°C

Parameter		Cymphol		Ratings		Unit	Measuring	Deference		
Parai	neter	Symbol	Min	Туре	Max.	Unit	Temp.	Reference		
Operatin	g voltage	Vo	8.7	9.0	9.3	V	<b>25</b> ℃			
Frame fr	equency	f		75	-	Hz		(Note10-2)		
Contrast ratio		Cr( <i>θ</i> =20°, <i>Φ</i> =90° or 270°)	3	-	-	-	<b>25</b> ℃	(Note10-3)		
	Turn on	Turn on	Turn on	+	-	-	300	ms	<b>25</b> ℃	
Response		t <sub>on</sub>	-	-	1	1115	0℃	(Note10-4)		
time	Turn off	+	-	-	300	me	<b>25</b> ℃	(Note 10-4)		
	Turn off	t <sub>off</sub>	-	-	1	ms	0℃			
Viewing	Up-down	<i>θ</i> 1 ( <i>Φ</i> =90° or 270°)	-20		30	deg	<b>25</b> ℃	(Note10-5)		
angle (Cr≥2)	Left-right	<i>θ</i> 2 ( <i>Φ</i> =0° or 180°)	-30		30	deg	25℃	(Note 10-5)		

(Note10-1) The maximum and minimum ratings don't mean the LCD works well in the whole range of Vo. Vo must be adjusted to optimize the viewing angle and contrast. Refer to definition of drive voltage, refer to 10.2.

(Note10-2) The frequency shouldn't be too low to avoid flicker. Refer to definition of drive voltage, refer to 10.2.

(Note10-3) Refer to 10.2/10.3/10.4/10.5.

(Note10-4) The selected state is dark and non-selected state is white (or bright) with positive type, reversely the selected state is white (or bright) and non-selected state is dark with negative type. Refer to 10.6 definition of response time.

(Note10-5) Generally the viewing direction is 6:00 or12:00, sometimes 3:00 or 9:00. The range of left to right and up to down based on Cr=2 show the viewing angle. Viewing angle range isn't the range of defects inspection. Refer to 10.4.



### 10.2 Definition of drive voltage

#### (1) Definition of drive voltage and waveform

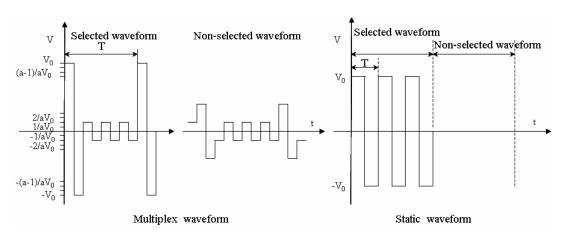


Fig.1 Definition of drive voltage and waveform

Operating voltage: V<sub>o</sub> Frame frequency: f=1/T

Duty: 1/N Bias: 1/a

#### (2) Operating voltage: Vo

TIANMA can evaluate whether the LCD can be redesigned to obtain customer preferable performance if customer's LCD drive voltage isn't adjustable.

# 10.3 Optical characteristics measurement equipment and method

The setup and test method are showed in fig.2. Test methods are different according to different illumination mode.

Transmissive mode: light resource is placed at the back of LCD.

Reflective mode and transflective mode: light resource is placed at the front side of LCD.

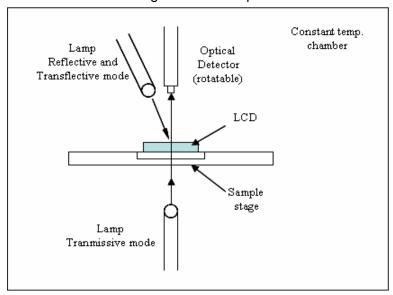


Fig.2 Optical characteristics measurement equipment



The chamber temperature, light resource and driving signal should be stable before testing. If test the characteristics under high or low temperature, the test system should be stable for more than 10 minutes before testing.

# 10.4 Definition of viewing direction

Refer to the graph below marked by  $\theta$  and  $\Phi$ 

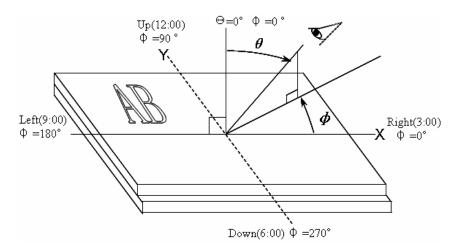


Fig.3 Definition of viewing direction

#### 10.5 Definition of contrast ratio

Contrast ratio can be calculated by the formula (10-1) below for positive type. If the LCD is negative type, Cr  $(\theta, \Phi)$  is equal to luminance  $(\theta, \Phi, \theta)$  non-selected state) divided by luminance  $(\theta, \Phi, \theta)$  selected state). Note3-4 shows the relationship between selected state, non-selected state and bright state, dark state.

$$Cr(\theta, \phi) = \frac{L_2}{L_1} = \frac{Luminance(\theta, \phi) \text{ (Bright state)}}{Luminance(\theta, \phi) \text{ (Dark state)}}$$
(10-1)

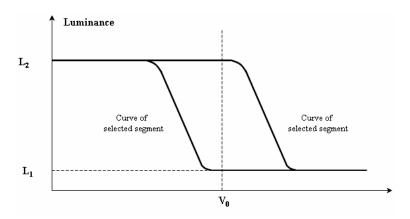


Fig.4 Electro-optical characteristic (EOC) graph (positive type)

# 10.6 Definition of response time

Turn on time (rise time):  $t_{on} = t_d + t_r$  (from non-selected state to selected state) Turn off time (fall time):  $t_{off} = t_D + t_R$  (from selected state to non-selected state)



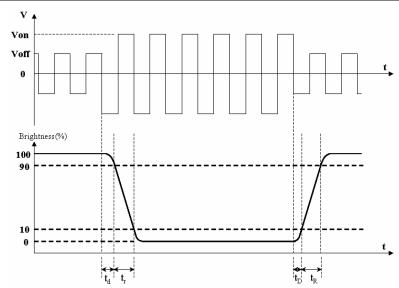


Fig.5 Definition of response time (positive type)

# 10.7 Definition of viewing angle

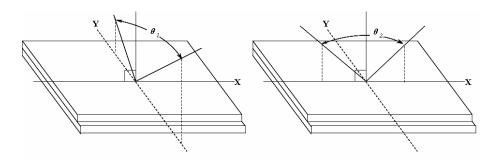


Fig 6 Definition of viewing angle

 $\theta_1$  ——range of viewing angle from up to down

 $\theta_2$  ——range of viewing angle from left to right.



# 11 Reliability

# 11.1 Content of Reliability Test

Ta=25℃

No	Test Item	Test condition	Criterion		
1	High Temperature Storage	80℃±2℃ 120H Restore 2H at 25℃ Power off			
2	Low Temperature Storage	-30°C±2°C 120H Restore 2H at 25°C Power off			
3	High Temperature Operation	70°C±2°C 120H Restore 2H at 25°C Power on			
4	Low Temperature Operation	-20°C±2°C 120H Restore 4H at 25°C Power on	After testing, cosmetic and electrical defects		
5	High Temperature & Humidity Operation	40℃±2℃ 90%RH 120H Power on	should not happen.		
6	Temperature Cycle	-30°C → 25°C → 80°C 30min 5min 30min  after 10cycle, Restore 2H at 25°C  Power off			
7	Vibration Test	10Hz~150Hz, 100m/s <sup>2</sup> , 120min			
8	Shock Test	Half-sine wave,300m/s <sup>2</sup> ,11ms			
9	Drop Test(package state)	1000mm, concrete floor,1corner, 3edges, 6 sides each time	1.After testing, cosmetic and electrical defects should not happen. 2.the product should remain at initial place 3.Product uncovered or package broken is not permitted.		

#### Notes:

- 1. Each test item applies for a test sample only once, The test sample can not be used again in any other test item.
- 2. The test sample is inspected after 2 hours or more storing at room temperature and room humidity after each test item is finished.
- 3. The criteria refer to 11.2.

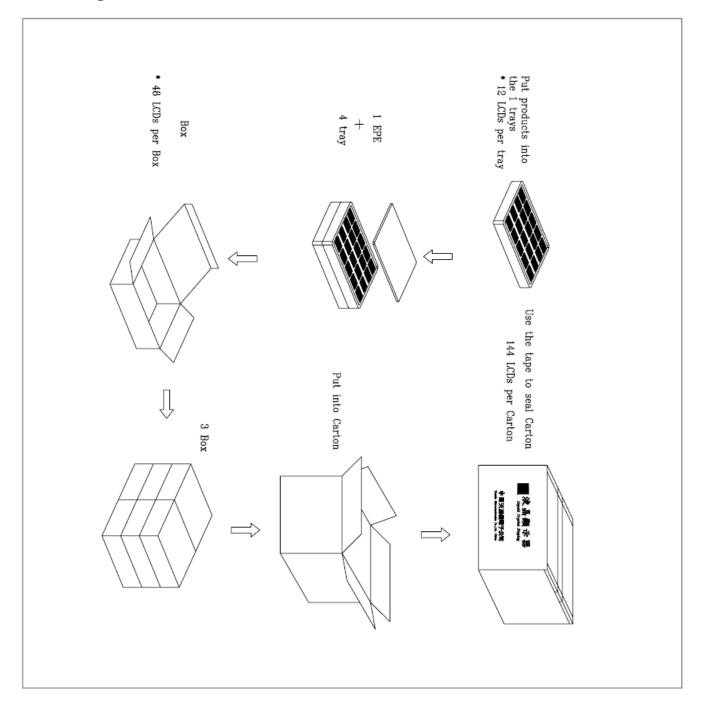


# 11.2 Inspection of criteria

Remark NO.	Content
1	Functional test is OK.  Missing Segment, shorts, unclear segment, nondisplay, display abnormally, liquid crystal leak are unallowable.
2	After testing, cosmetic defects should not happen, no low temperature bubbles, seal loose and fall, frame rainbow, ACF bubble growing are unallowable in the appearance test.
3	Total current consumption should not be over 10% of initial value.
4	After tests being executed, Contrast must be larger than 70% of its initial value prior to the tests.
5	No glass crack, chipped glass, end seal loose frame crack and so on.
6	No structure loose and fall.



# 12 Package





# 13 Quality level

#### 13.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects (such as no display, abnormal display, open or missing segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

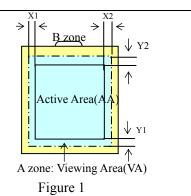
Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

# 13.2 Definition of inspection range

For LCD defects, dividing two areas to make a judgment (according figure 1).

A zone : Inside Viewing area B zone : Outside Viewing area

X1(A.A~V.A): 2mm X2(A.A~V.A): 2mm Y1(A.A~V.A): 2mm Y2(A.A~V.A): 2mm



#### 13.3 Inspection items and general notes

	o moposition from and gonoral notes							
General notes	①Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and TIANMA. ②Viewing area should be the area which TIANMA guarantees. ③Limit sample should be prior to this Inspection standard. ④Viewing judgment should be under static pattern. ⑤Inspection conditions Inspection distance: 250 mm (from the sample) Inspection angle : 45 degrees in 6 o'clock direction (all defects in viewing area should be inspected from this direction)							
	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble  Pinhole, Bright spot, Black spot, Black line, The color of a small area is different from the remainder. phenomenon doesn't change with voltage							
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage						
Inspection items	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass						
	Functional defect	no display, display abnormally, open or missing segment, short circuit, False viewing direction						
	Glass defect	Glass crack, Shaved corner of glass, Surplus glass						
	Segment defect	Pin holes or cracks in segment, Transformation of segment						
	PCB defect	Components assembly defect						



13.4 Outgoing Inspection level

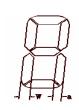
Outgoing Inspection	Inspection conditions	Inspection						
standard	Inspection conditions –		Max.	Unit	ᆜ	AQL		
Major Defects	See 13.3 general notes	S	See 13.5		See 13.5		Ш	0.65
Minor Defects	or Defects See 13.3 general notes		See 13.5		=	1.5		
Note: Sampling standard conforms to GB2828								

# 13.5 Inspection Items and Criteria

				Judgment standard						
	Inspection	on items		Catagony	Acceptable number					
			Category	A zone	B zone					
	Black spot,White spot, Bright Spot,			Ф≦0.10	Neglected					
1	Pinhole, Foreign Particle, Particle in or on glass,	a e	В	B 0.10<Φ≦0.20 3		Neglected				
	Scratch on glass	$\Phi = (a+b)/2(m$	С	0.20<Ф	0					
	Black line, White	4	Α	W≦0.02	Neglected					
2	line, Particle Between Polarizer and glass, Scratch	and glass, Scratch		0.02 <w≤0.05 L≤3.0</w≤0.05 	3	Neglected				
	on glass			W>0.05 or L>3.0	0					
				Ф≦0.2	Neglected					
		$\begin{array}{c c} & b \\ \hline \end{array}$	В	0.2<Φ≦0.3	2	Neglecte				
3	Contrast variation		С	0.3<Φ≦0.4	1	d				
		$\Phi = (a+b)/2(mm)$	D	0.4<Ф	0					
			Total defective point(B,C)		3					
4	Bubble inside cell			any size	none	none				
5	Polarizer defect (if Polarizer is used)	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.	Re	fer to item 1 and item 2.						
		Bubble, dent and	Α	Ф≦0.3	Neglected	Neglecte				
		convex	В	0.3<Φ≦0.7	2	d d				

			С	С 0.7<Ф		0			
	Surplus	Stage surplus glass	b≦0.3mm						
6	glass	Surrounding surplus glass	Sh	embling.					
7	Open segment or op	oen common	No	t permitted					
8	Short circuit		No	t permitted					
9	False viewing direct	ion	No	t permitted					
10	Contrast ratio uneve	en	Ac	cording to the limit	specin	nen			
11	Crosstalk		According to the limit specimen						
12	Black /White spot(display)			Refer to item 1					
13	Black /White line(dis	splay)	Refer to item 2						
14		- + a		not counted	Ма	x.3 dots allowed			
	Pin holes and			x<0.1mm	0.1	mm≤x≤0.2mm			
	cracks in segment	a-1 F-		x=(	=(a+b)/2		Max.3 dots		
		-D		not counted	Max.2 dots allowed each segment		allowed		
				A<0.1mm	0.1	mm≤A≤0.2mm D<0.25mm			
15	Transformation of segment	-		not counted		1 defect allowed each segment			
				x<0.1mm	0.1	mm≤x≤0.2mm			
		*			(a+b)/2		Max.3 defects		
		D-1+1-0.		not counted Max.1 defect allowed each segment			allowed		
				a<0.1mm	0.1	mm≤a≤0.2mm D>0			





0.8W≤a≤1.2W a=measured value of width W=nominal value of width

Max.2 defects allowed

				Judgment standard	
		Inspection items		Category(application: B zone)	Acceptable number
17	Glass defect crack	①The front of lead terminals  b  c	В	a≤ t, b≤1/5W, c≤3mm  Crack at two sides of lead terminals should not cover patterns and alignment mark	Max.3 defects allowed
		②Surrounding crack—non-contact side  seal  c h a t  C h a t  Inner border line of the seal  Outer border line of the seal	b <	< Inner borderline of the seal	



3 Surrounding crack— contact side  seal  t  c  t  Inner border line of the seal  Outer border line of the seal	b <	< Outer borderline of the seal	
4 Corner w b c	В	$a \le t$ , $b \le 3.0$ , $c \le 3.0$ Glass crack should not cover patterns u and alignment mark and patterns.	



Inspection items			Judgment standard
mapacitan nama			Category(application: B zone)
18	PCB defect	Component soldering: No cold soldering, short, open circuit, burn, tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2) lead defect: The lead lack must be less than 1/3 of its width; The lead burn must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted	Component Soldering pad Lead L1>0 L2>0 L2>0
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	Soldering tin is not permit in this area  Soldering tin is not permit in this area  Socket  Base Board
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat



### 14 Precautions for Use of LCD Modules

### 14.1 Handling Precautions

- 14.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 14.1.2 Liquid in LCD is hazardous substance, if the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, thoroughly and promptly wash it off using soap and water.
- 14.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 14.1.4 Don't touch, push or rub the exposed polarizer covering the display surface of the LCD module with anything harder than an HB pencil lead, the polarizer is soft and easily scratched, handle it carefully.
- 14.1.5 Don't put or attach anything on the display area to avoid leaving any marks on.
- 14.1.6 If the display surface is contaminated or becomes dusty, breathe on the surface and gently wipe it with a soft dry cloth. do not scrub hard to avoid damage the surface. If still not completely clear, moisten cloth with one of the following solvents:
  - Isopropyl alcohol
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 14.1.7 Do not attempt to disassemble the LCD Module.
- 14.1.8 If the logic circuit power is off, do not apply the input signals.
- 14.1.9 Avoid using the same display pattern long time (continous ON segment). Software must be prepared so that the pattern will be changed
- 14.1.10 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
  - a. Be sure to ground the body and electric appliances when handling the LCD Modules. It is preferable to use conductive mat on table and wear cotton clothes or conductive processed fibre. Synthetic fibre is not recommended.
  - b. Tools required for assembly, such as soldering irons, must be properly ground.
  - c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
  - d. The LCD Module is coated with a film to protect the display surface. Be careful and slow when peeling off this protective film since static electricity may be generated. It is recommended to use ionic fan or machine when operating. It is recommended to remove the protection foil slowly (> 3 sec.).
  - e. It is preferable to wear gloves etc, to avoid damaging the LCD. Please do not touch electrodes with bare hands or avoid any other contamination.



# 14.2 Storage precautions

- 14.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 14.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :  $5^{\circ}$ C  $\sim$  40  $^{\circ}$ C

Relatively humidity: ≤80%

- 14.2.3 The LCD modules should be stored in a clean environment or room, free from acid, alkali and harmful gas.
- 14.2.4 Store the module in anti-static electricity container and without any physical load.

# 14.3 Transportation precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

### 14.4 Soldering

- 14.4.1 Use the high quality solders, only solder the I/O terminals.
- 14.4.2 No higher than 280 ℃ and time less than 3-4 second during soldering.
- 14.4.3 Rewiring: no more than 3 times.
- 14.4.4 when you remove connector or cable soldered to I/O terminals, please confirm that solder is fully melted. If you remove by force, electrodes at I/O terminals may be damaged (or stripped off). It is recommended to use solder suction machine.



# 15. LCD Module Part Numbering System

TM 12864 J1	CCC	WG	WA
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1 2 3 4 5 6 7 8 9

NO.	Explanation			
1)	TIANMA module indicating			
2	Module type: 128 columns X 64 rows			
3	TIANMA module series			
	LCD type			
4	С	positive, FSTN		
(5)	Backlight type			
9	С	Transflective ,LED		
6	Temperature range			
0	W	Wide temperature		
7	Technology			
	G	COG		
8	The color of backlight			
0	W	White		
9	Function choice			
9	Α	Base function		